

Description

The HN6971 uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

General Features

 $V_{DS} = -60V I_{D} = -20 A$

 $R_{DS(ON)} < 60 m\Omega$ @ V_{GS} =-10V

Application

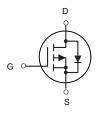
Battery protection

Load switch

Uninterruptible power supply



DFN3X3-8L



P-Channel MOSFET

Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
HN6971	DFN3X3-8L	HN6971 XXYYS	5000

Absolute Maximum Ratings (TC=25°C unless otherwise specified)

Symbol	Parameter	Rating	Units
VDS	Drain-Source Voltage	-60	V
VGS	Gate-Source Voltage	±20	V
I _D @T _C =25°C	Continuous Drain Current, V _{GS} @ -10V ¹	-20	А
I _D @T _C =100°C	Continuous Drain Current, V _{GS} @ -10V ¹	-12	А
IDM	Pulsed Drain Current ²	-30	А
EAS	Single Pulse Avalanche Energy ³	18.1	mJ
IAS	Avalanche Current	-13	А
P _D @T _C =25°C	Total Power Dissipation⁴	25	W
P _D @T _A =25°C	Total Power Dissipation ⁴	2	W
TSTG	Storage Temperature Range	-55 to 150	°C
TJ	Operating Junction Temperature Range	-55 to 150	℃



Electrical Characteristics (T_J=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit		
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =-250uA	-60			V		
$\triangle BV_{DSS}/\triangle T$	BV _{DSS} Temperature Coefficient	Reference to 25°C , I _D =-1mA		-0.023		V/°C		
В	Static Drain-Source On-Resistance ²	V _{GS} =-10V , I _D =-10A		49	60	m()		
R _{DS(ON)}	Static Drain-Source On-Resistance	V _{GS} =-4.5V , I _D =-6A		61	75	mΩ		
V _{GS(th)}	Gate Threshold Voltage	V -V I - 2504	-1.2		-2.5	V		
$\triangle V_{GS(th)}$	V _{GS(th)} Temperature Coefficient	$V_{GS}=V_{DS}$, $I_D=-250uA$		4		mV/°C		
	Drain Source Leekage Current	V _{DS} =-24V , V _{GS} =0V , T _J =25°C	V _{DS} =-24V , V _{GS} =0V , T _J =25°C	V _{DS} =-24V , V _{GS} =0V , T _J =25°C -			-1	
I _{DSS}	Drain-Source Leakage Current	V_{DS} =-24V , V_{GS} =0V , T_{J} =55 $^{\circ}$ C			-5	uA		
I _{GSS}	Gate-Source Leakage Current	$V_{GS}=\pm 20V$, $V_{DS}=0V$			±100	nA		
gfs	Forward Transconductance	V _{DS} =-5V , I _D =-15A		12		S		
Qg	Total Gate Charge (-4.5V)			6.1				
Q _{gs}	Gate-Source Charge	V _{DS} =-15V , V _{GS} =-4.5V , I _D =-15A		3.1		nC		
Q _{gd}	Gate-Drain Charge			1.8		1		
T _{d(on)}	Turn-On Delay Time			2.6				
Tr	Rise Time	V_{DD} =-15V , V_{GS} =-10V , R_{G} =3.3 Ω ,		8.6				
$T_{d(off)}$	Turn-Off Delay Time	I _D =-15A		33.6		ns		
T _f	Fall Time			6				
C _{iss}	Input Capacitance			585				
C _{oss}	Output Capacitance	V _{DS} =-15V , V _{GS} =0V , f=1MHz		100		pF		
C _{rss}	Reverse Transfer Capacitance			85				

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Is	Continuous Source Current ^{1,5}	V =V =0V Force Current			-20	Α
I _{SM}	Pulsed Source Current ^{2,5}	V _G =V _D =0V , Force Current			-30	Α
V_{SD}	Diode Forward Voltage ²	V _{GS} =0V , I _S =-1A , T _J =25°C			-1.2	V
t _{rr}	Reverse Recovery Time	IF=-15A , dI/dt=100A/μs ,		6.1		nS
Q _{rr}	Reverse Recovery Charge	T _J =25°C		1.4		nC

Note:

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width $\,\leq\,300\text{us}$, duty cycle $\,\leq\,2\%$
- 3. The EAS data shows Max. rating . The test condition is V_{DD} =-25V, V_{GS} =-10V,L=0.1mH,I_{AS}=-19A
- 4.The power dissipation is limited by 150°C junction temperature
- 5. The data is theoretically the same as I_D and I_{DM} , in real applications, should be limited by total power dissipation.



Typical Characteristics

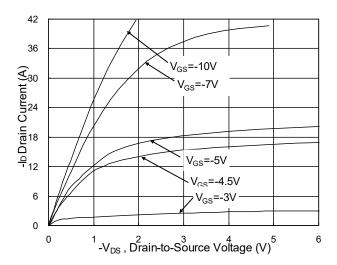


Fig.1 Typical Output Characteristics

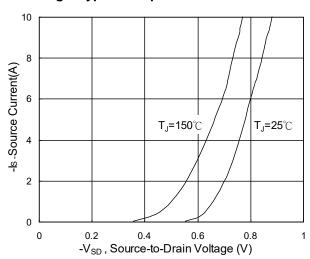


Fig.3 Forward Characteristics Of Reverse

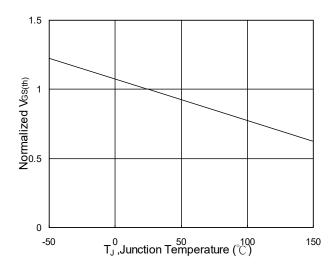


Fig.5 Normalized V_{GS(th)} vs. T_J

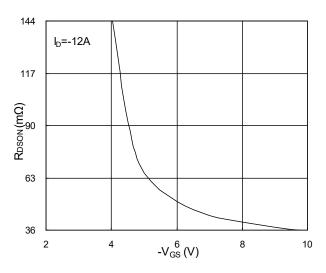


Fig.2 On-Resistance v.s Gate-Source

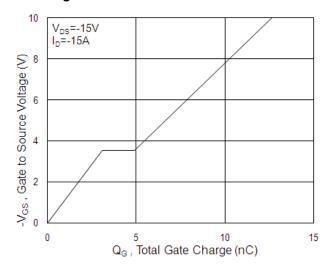


Fig.4 Gate Charge Characteristics

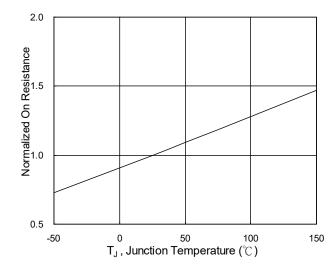
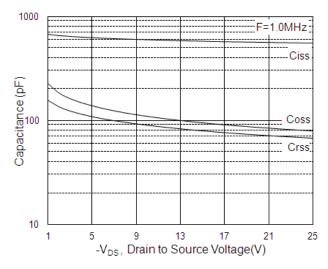


Fig.6 Normalized R_{DSON} vs. T_J



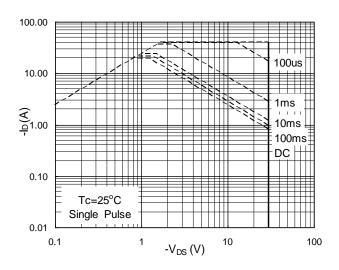


Fig.7 Capacitance

Fig.8 Safe Operating Area

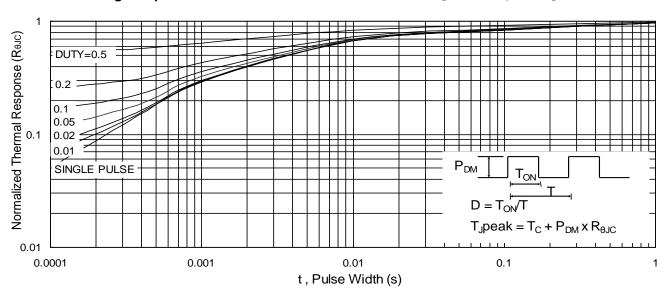


Fig.9 Normalized Maximum Transient Thermal Impedance

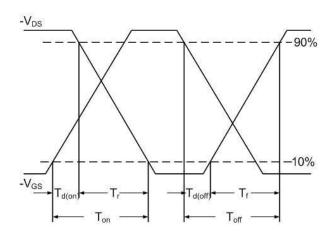


Fig.10 Switching Time Waveform

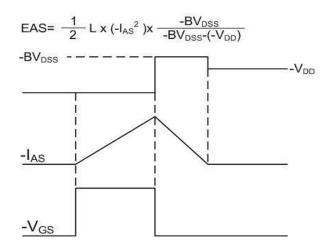
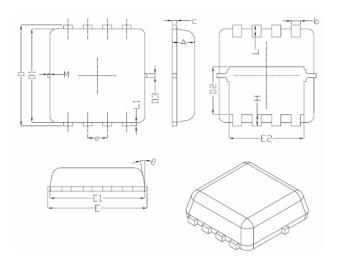


Fig.11 Unclamped Inductive Switching Waveform



DFN3X3-8L Package Information



Symbol	Dimensions In Millimeters			
Symbol	Min.	Nom.	Max.	
A	0.70	0.75	0.80	
b	0.25	0.30	0.35	
С	0.10	0.15	0.25	
D	3.25	3.35	3.45	
D1	3.00	3.10	3.20	
D2	1.48	1.58	1.68	
D3	-	0.13	-	
E	3.20	3.30	3.40	
E1	3.00	3.15	3.20	
E2	2.39	2.49	2.59	
e	0.65	BSC		
Н	0.30	0.39	0.50	
L	0.30	0.40	0.50	
L1	-	0.13	-	
M	*	*	0.15	
θ		10 [°]	12 [°]	



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